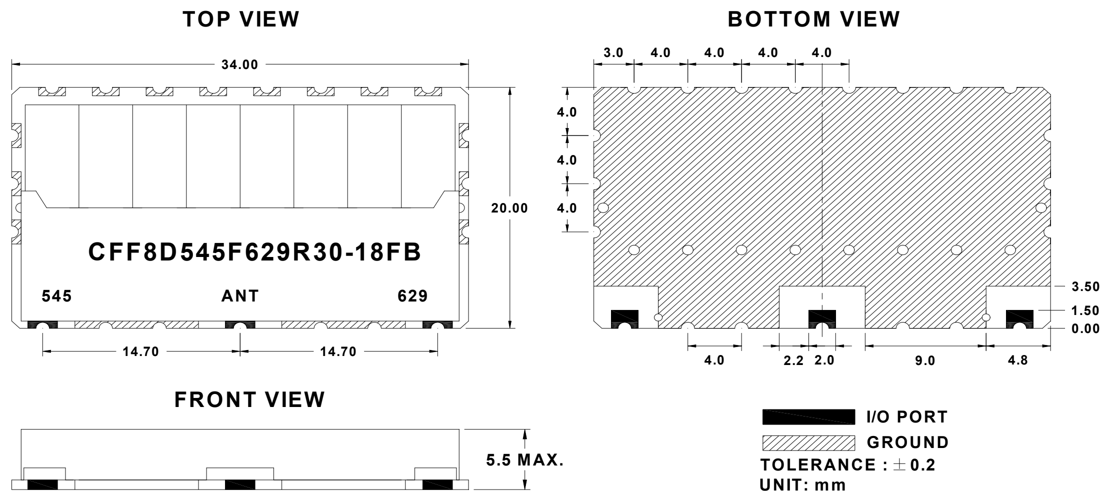
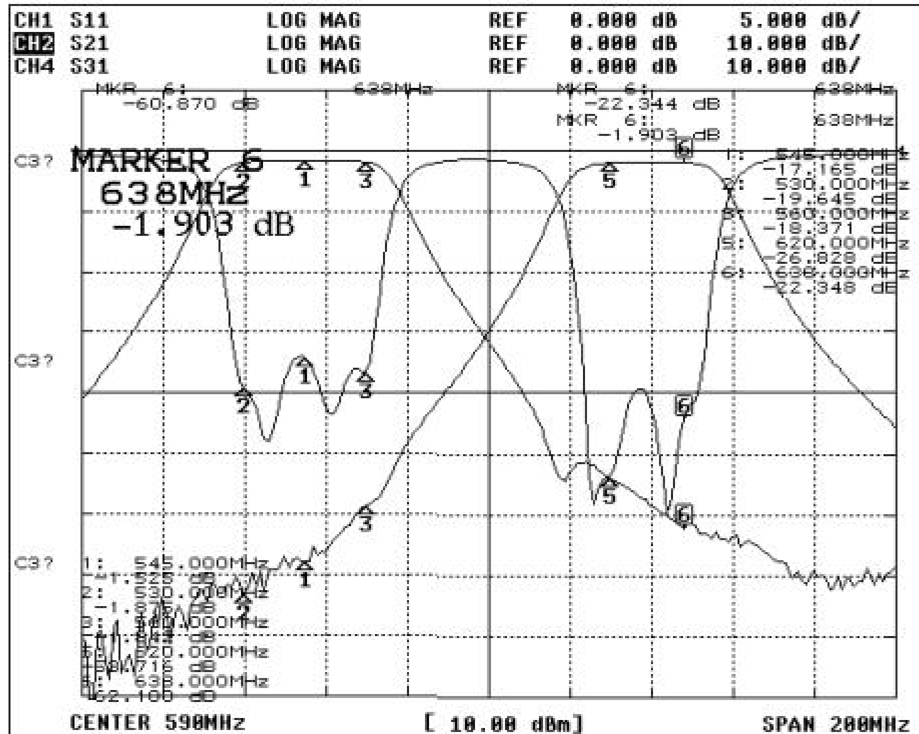
Electrical Specification

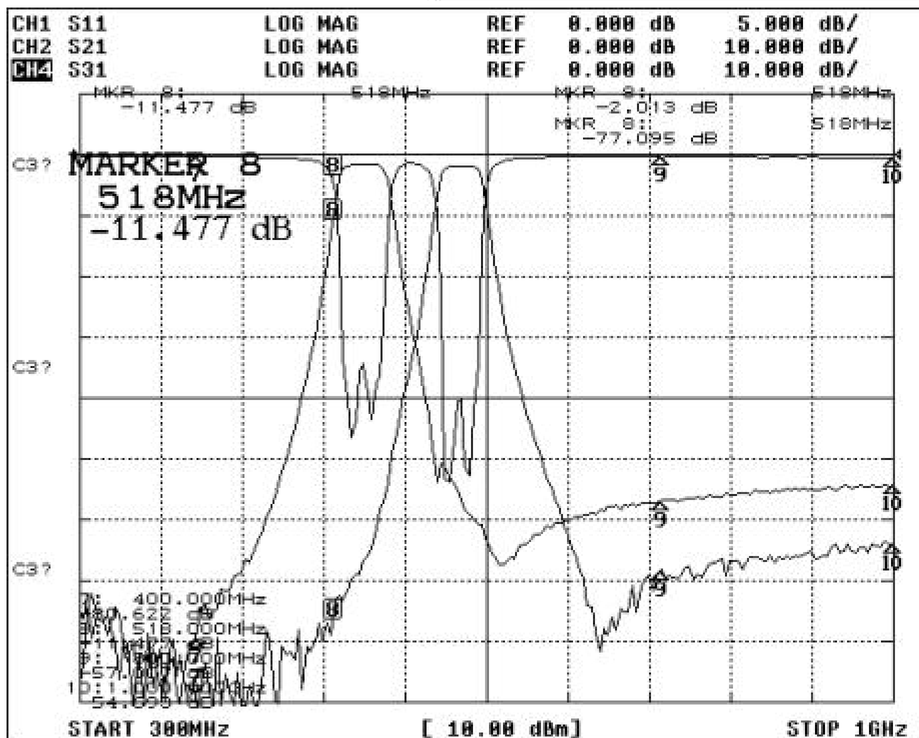
ITEMS	ANT >> Low	ANT >> High	UNIT
Center Frequency [fo]	545.0	629.0	MHz
Bandwidth [BW]	fo ±15.0 [530.0 ~ 560.0]	fo ±9.0 [620.0 ~ 638.0]	MHz
Insertion Loss in BW	3.0	3.0	dB max
Ripple in BW	1.0	1.0	dB max
Return Loss in BW	10.0	10.0	dB min
Attenuation ☑ Absolute Value ☐ Relative Value	48.0 dB min. @ [620.0 ~ 638.0]	55.0 dB min. @ [530.0 ~ 560.0]	MHz
	30.0 dB min. @ [DC ~ 400.0]	30.0 dB min. @ [DC ~ 500.0]	MHz
	25.0 dB min. @ [800.0 ~1000.0]	25.0 dB min. @ [766.0 ~1000.0]	MHz
	10.0 dB min. @ [518.0 ~]	dB min. @ [~]	MHz
Isolations	55.0 dB min @ [530.0 ~ 560.0]		MHz
	48.0 dB min @ [620.0 ~ 638.0]		MHz
Group Delay Variation			ns max
Input Power	3.0		W max.
In/Out Impedance	50 Ω		
Operation Temperature Range	-40℃ to +85℃		

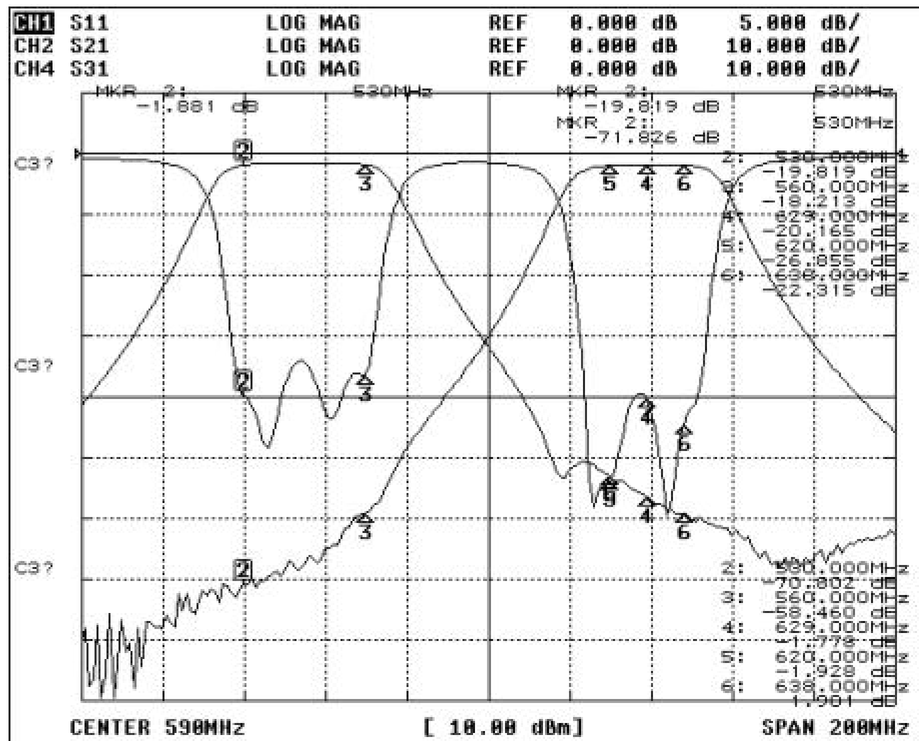
Mechanical Specification

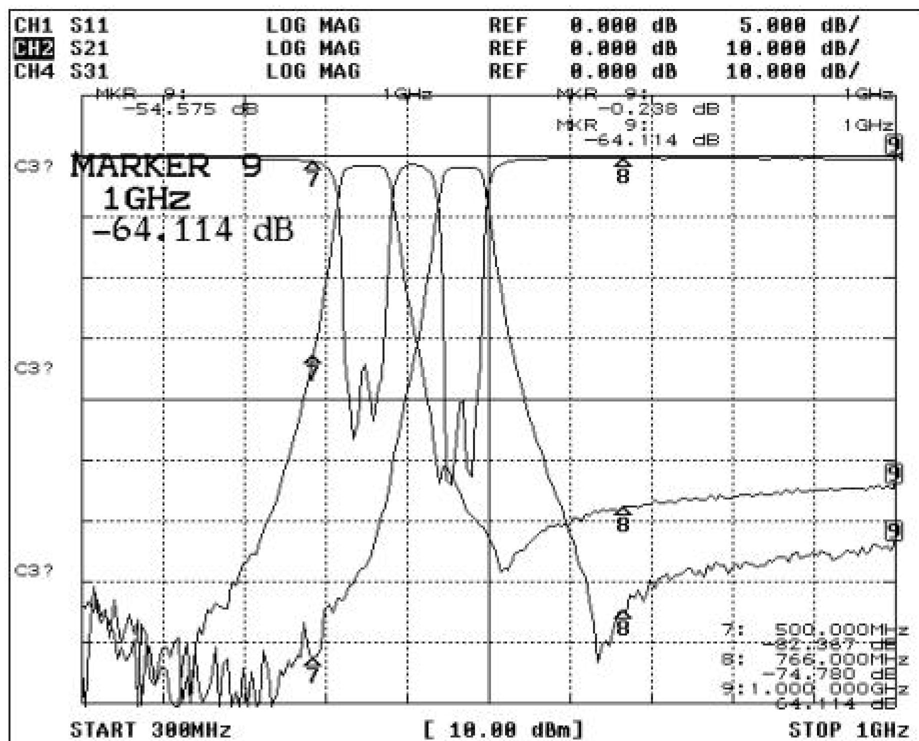


Plot Data

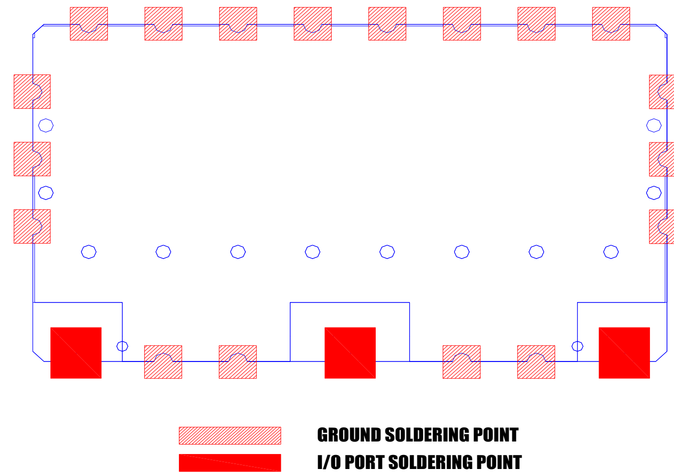




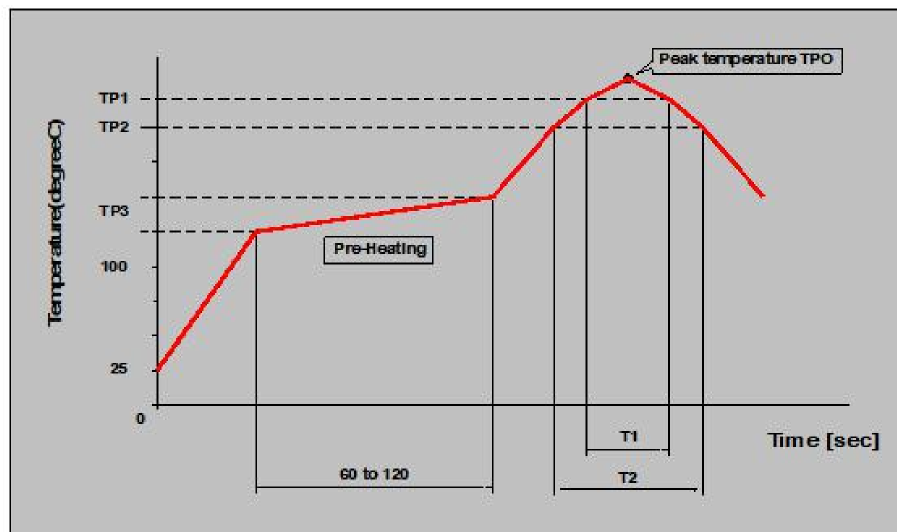

CH1 S11 LOG MAG REF 0.000 dB 5.000 dB/
CH2 S21 LOG MAG REF 0.000 dB 10.000 dB/
CH4 S31 LOG MAG REF 0.000 dB 10.000 dB/
MKR 2: -1.881 dB 530MHz
MKR 2: -19.819 dB 530MHz
MKR 2: -71.826 dB 530MHz
2: 530.000MHz -19.819 dB
3: 560.000MHz -18.213 dB
4: 629.000MHz -20.165 dB
5: 620.000MHz -26.855 dB
6: 638.000MHz -22.315 dB
2: 530.000MHz -70.802 dB
3: 560.000MHz -58.460 dB
4: 629.000MHz -1.778 dB
5: 620.000MHz -1.928 dB
6: 638.000MHz -1.901 dB
CENTER 590MHz
[10.00 dBm]
SPAN 200MHz


CH1 S11 LOG MAG REF 0.000 dB 5.000 dB/
CH2 S21 LOG MAG REF 0.000 dB 10.000 dB/
CH4 S31 LOG MAG REF 0.000 dB 10.000 dB/
MKR 9: -54.575 dB 1GHz
MKR 9: -0.238 dB 1GHz
MKR 9: -64.114 dB 1GHz
MARKER 9
1GHz
-64.114 dB
7: 500.000MHz -82.387 dB
8: 766.000MHz -74.780 dB
9: 1.000 000GHz -64.114 dB
START 300MHz
[10.00 dBm]
STOP 1GHz

Recommanded PC Board Pattern



Soldering Condition



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

Reflow standard condition	TPO (°C)	TP1 (°C)	T1 (s)	TP2 (°C)	T2 (s)	TP3 (°C)
Sn-3Ag-0.5 solder	245+/-5	220	30 to 60	___	___	150 to 180
Test condition of reflow heat resistance	260+5/-0	240	20	220	70	150 to 180